

Product Change Notification / CENO-26WFQV556

Date:

21-Jul-2022

Product Category:

General Purpose FPGAs

PCN Type:

Manufacturing Change

Notification Subject:

CCB 5170 and 5170.001 Initial Notice: Qualification of MTAI as a new assembly site for selected A3P0xx, A3PN0xx, AGL0xxxx and AGLN0xxxx device families available in 68L VQFN (8x8x1mm) and 48L VQFN (6x6x1mm) packages.

Affected CPNs:

CENO-26WFQV556_Affected_CPN_07212022.pdf CENO-26WFQV556_Affected_CPN_07212022.csv

Notification Text:

PCN Status:Initial Notification

PCN Type: Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section. Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of MTAI as a new assembly site for selected A3P0xx, A3PN0xx, AGL0xxxx and AGLN0xxxx device families available in 68L VQFN (8x8x1mm) and 48L VQFN (6x6x1mm) packages.

Pre and Post Change Summary:

		Pre Change	Post Change			
		UTAC Dongguan Limited	Microchip Technology Thailand			
Assembly Site		(UDG)	(HQ)			
			(MTAI)			
Wire Material		CuPd	CuPdAu			
Die Attach Material		8200T	3280			
Molding Compound Material		G700HCD	G700LTD			
Lead-Frame	For 68L	C7025	A194			
Material	For 48L	A194	A194			
Lead-Frame	For 68L	For 68L: 125x125 mils	122x122 mils			
	For 48L	For 48L: 193x193 mils	193 x 193 mils			
	See	e attached Pre and Post Chang	ge Comparison			
DAP Surface Prep		Ag Ring Plating	Ag Ring Plating			

Impacts to Data Sheet:None

Change ImpactNone

Reason for Change:To improve manufacturability by qualifying MTAI as a new assembly site.

Change Implementation Status: In Progress

Estimated Qualification Completion Date: October 2022

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	July 2022							Octo	ber	2022	
Workweek	2 8	2 9	3 0	3 1	3 2		4 1	4 2	4 3	4 4	4 5
Initial PCN Issue			х								

Date						
Qual Report						×
Availability						X
Final PCN Issue						~
Date						Х

Method to Identify Change: Traceability code

Qualification Plan:Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History: July 21, 2022: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

PCN_CENO-26WFQV556_Pre and Post Change_Summary.pdf PCN_CENO-26WFQV556_Qualification Plan Summary.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to <u>receive Microchip PCNs via email</u> please register for our PCN email service at our PCN home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the PCN FAQ section.

If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections. CENO-26WFQV556 - CCB 5170 and 5170.001 Initial Notice: Qualification of MTAI as a new assembly site for selected A3P0xx, A3PN0xx, AGL0xxxx and AGLN0xxxx device families available in 68L VQFN (8x8x1mm) and 48L VQFN (6x6x1mm) packages.

Affected Catalog Part Numbers (CPN)

A3P030-1QNG48 A3P030-2QNG48 A3P030-QNG48 A3P015-QNG68 A3P030-1QNG68 A3P030-2QNG68 A3P030-QNG68 A3P030-1QNG48I A3P030-2QNG48I A3P030-QNG48I A3P015-QNG68I A3P030-1QNG68I A3P030-2QNG68I A3P030-QNG68I A3PN030-ZQNG48I A3PN030-ZQNG48 A3PN030-ZQNG68I A3PN030-ZQNG68 A3PN010-1QNG48I A3PN010-1QNG48 A3PN010-2QNG48I A3PN010-2QNG48 A3PN010-QNG48I A3PN010-QNG48 A3PN015-1QNG68I A3PN015-1QNG68 A3PN015-2QNG68I A3PN015-2QNG68 A3PN015-QNG68I A3PN015-QNG68 A3PN020-1QNG68I A3PN020-1QNG68 A3PN020-2QNG68I A3PN020-2QNG68 A3PN020-QNG68I A3PN020-QNG68 AGL030V2-QNG48 AGL030V5-QNG48 AGL015V2-QNG68 AGL015V5-QNG68 AGL030V2-QNG68 AGL030V5-QNG68 AGL030V2-QNG48I AGL030V5-QNG48IX94 AGL030V5-QNG48I AGL030V2-QNG68I

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AGLU3UV5-QNG68I AGLN010V2-QNG48IX11 AGLN010V2-QNG48IX94 AGLN010V2-QNG48I AGLN010V2-QNG48PU33 AGLN010V2-QNG48 AGLN010V5-QNG48I AGLN010V5-QNG48Z204 AGLN010V5-QNG48 AGLN015V2-QNG68I AGLN015V2-QNG68 AGLN015V5-QNG68IPU88 AGLN015V5-QNG68IPZ88 AGLN015V5-QNG68I AGLN015V5-QNG68 AGLN020V2-QNG68I AGLN020V2-QNG68PS16 AGLN020V2-QNG68 AGLN020V5-QNG68I

AGLN020V5-QNG68